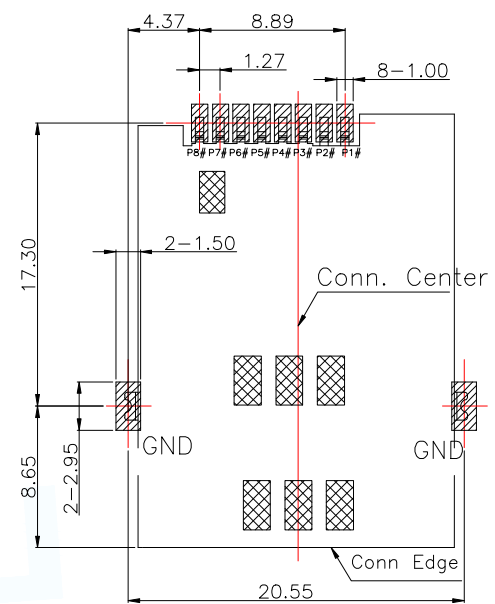
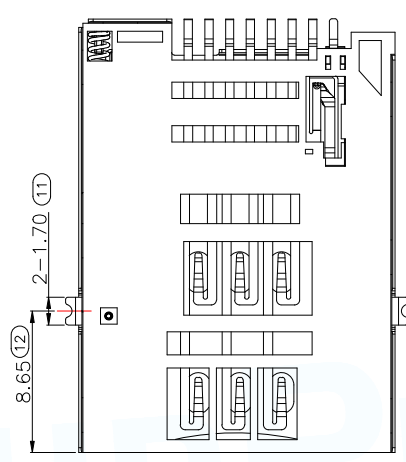
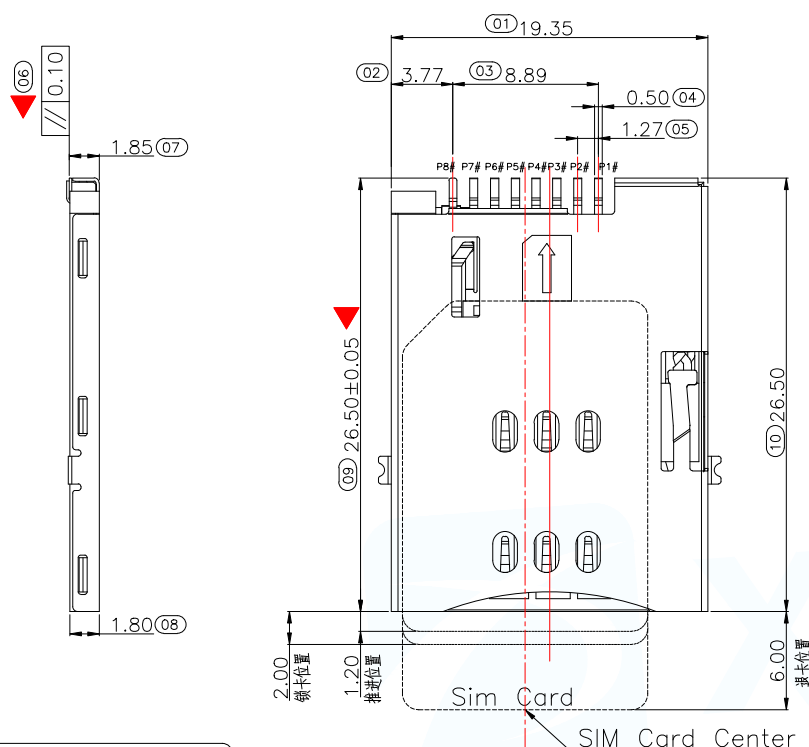


MAPX	MODIFICATION	DATE	DRAW	APPROVE

A
B
C
D
E
F
G
H
I
J

A
B
C
D
E
F
G
H
I
J



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

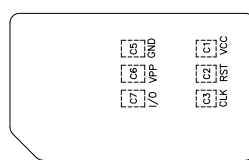
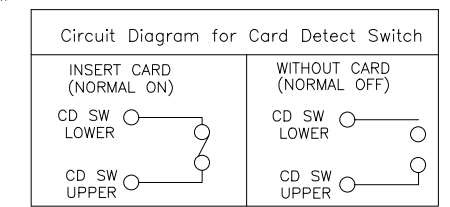
- SOLDER AREA
- NONE CIRCUIT DIAGRAM AREA

NOTES:

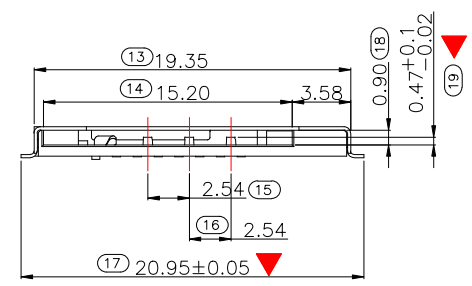
MATERIAL:
 Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 CD PIN: Copper Alloy
 Shell: STAINLESS

PLATING:
 Contact: Plated Ni , contact point gold plated G/F, welding feet Matte tin
 Shell: Plated Ni Overall Plated G/F Selective Contact Area
 CD PIN: Plated Ni, tin feet, contact point brush gold

Electrical:
 Current Rating :0.5A AC/DC max.
 Voltage Rating :50V AC/DC
 Ambient Temperature Range :-20°C~+60°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩ max.
 Insulation Resistance:1000MΩ min./500VDC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5°

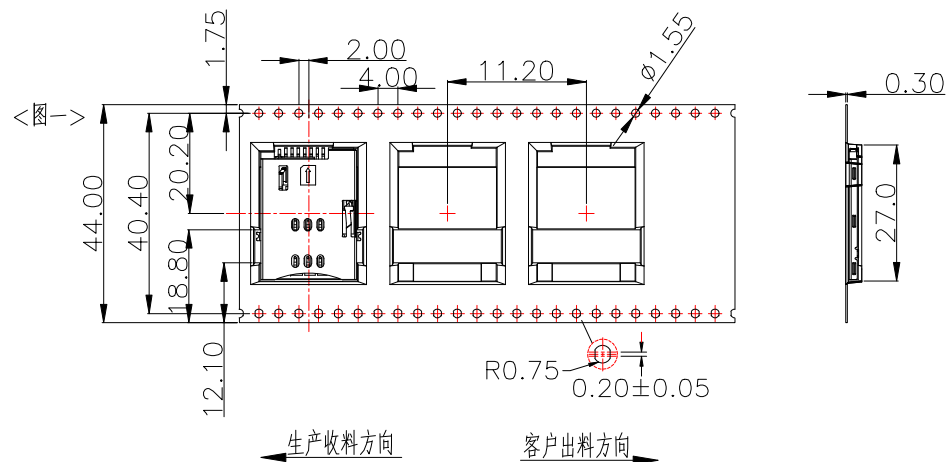


SIM 示意图
芯片面朝下视图



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL

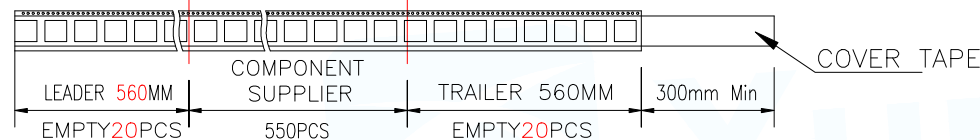
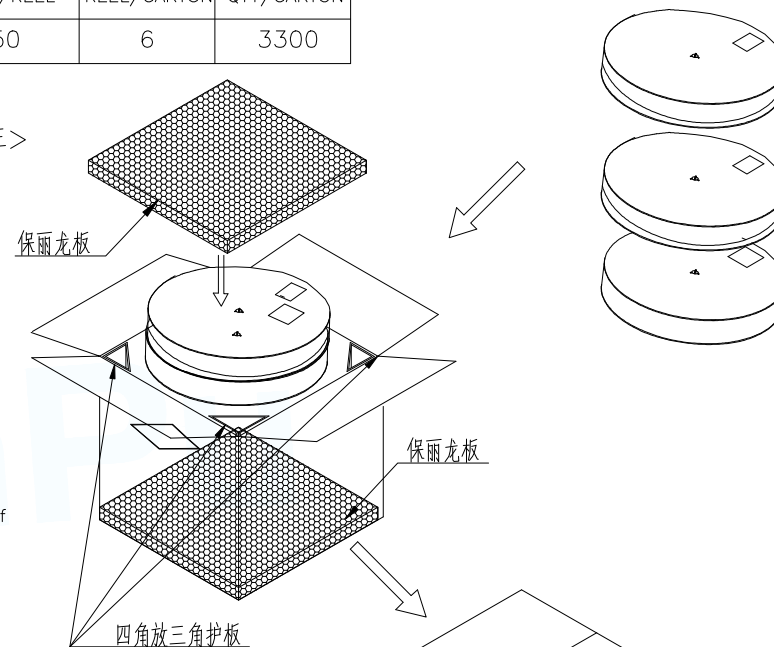
MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: SIM PUSH H1.8客户图	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	SIM-130-ARP8H18
DECIMALS:	ANGLES:	DWN		
.X:±0.30	X.':±2°	CHKD		
.XX:±0.20	X.X':±1°	APVD		
.XXX:±0.10		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		Website address	REV:A	



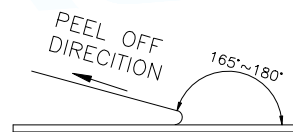
<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

<图三>



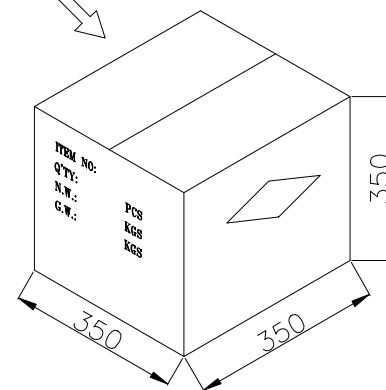
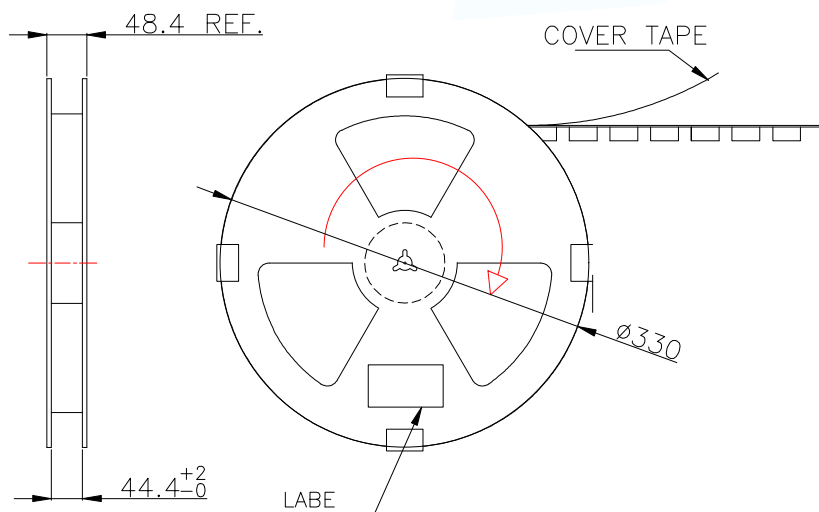
COVER TAPE PEELING FORCE: 20gf~120gf



NOTE:

- 依<图一>示放置产品于下载中,每穴放置1PCS产品.
- 包装机包好后,在REEL的个等分点贴上胶带,以防止REEL张开,每REEL贴1PCS标签,如<图二>示
- 包装数量见如<TABLE 1>示
- 包装成箱见如<图三>示
箱底放保丽龙板,再依次将指定数量的卷装产品放入箱内,四角分别放入四个三角护板,最上层再放上保丽龙板.
- 封箱,在封好的纸箱上按客户要求写上料号,数量等

<图二>



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	TITLE: SIM PUSH H1.8客户图	
UNLESS OTHERWISE SPECIFIED TOLERANCES			PAR	SIM-130-ARP8H18
DECIMALS:	ANGLES:	DWN		
.X:±0.30	X.' :±2'	CHKD		
.XX:±0.20	X.X' :±1'	APVD		
.XXX:±0.10		SCALE 1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	
		Website address	REV:A	

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